CLAIM AMENDMENTS

1. (Currently Amended) A high-frequency power amplifier comprising:

a multilayer substrate ~~formed by laminating~~ including a plurality of laminated dielectric layers;

a wiring prohibited area ~~provided~~ located on at least one of ~~a~~ an obverse side and a reverse side of said multilayer substrate in which wiring is prohibited;

a first strip conductor ~~provided~~ located within said multilayer substrate;

a second strip conductor ~~provided such that its~~ located at a position, in a lamination direction of said multilayer substrate ~~is~~, different from that of said first strip conductor;

a via ~~for~~ electrically connecting said first strip conductor ~~and~~ to said second strip conductor; and

a first grounding conductor and a second grounding conductor disposed sequentially in ~~said~~ the lamination direction of said multilayer substrate and sandwiching said first strip conductor and said second strip conductor~~;~~, wherein at least one of said first grounding conductor and said second grounding conductor includes:

a first grounding conductor portion ~~provided~~ for said wiring prohibited area; and

a second grounding conductor portion ~~provided~~ for an area other than said wiring prohibited area ~~such~~ so that ~~a position of~~ said second grounding conductor portion is positioned, in ~~said~~ the lamination direction of said multilayer substrate ~~is~~, different from ~~that of~~ said first grounding conductor portion.

2. (Currently Amended) The high-frequency power amplifier according to claim 1, wherein said wiring prohibited area includes:

a first wiring prohibited area ~~provided~~ located on ~~said~~ the obverse side of said multilayer substrate; and

a second wiring prohibited area ~~provided~~ located on ~~said~~ the reverse side of said multilayer substrate ~~such that~~, said second wiring prohibited area ~~is disposed at a position at which it overlaps~~ overlapping said first wiring prohibited area ~~as~~, when viewed in ~~said~~ the lamination direction of said multilayer substrate~~;~~, wherein ~~a~~ length of said first wiring prohibited area in said lamination direction of said multilayer substrate is different from that of said second wiring prohibited area.

3. (Currently Amended) The high-frequency power amplifier according to claim 1, wherein said wiring prohibited area includes:

a first wiring prohibited area ~~provided~~ located on ~~said~~ the obverse side of said multilayer substrate; and

a second wiring prohibited area ~~provided~~ located on ~~said~~ the reverse side of said multilayer substrate ~~such that~~, said second wiring prohibited area ~~is disposed at a position at which it does~~ not ~~overlap~~ overlapping said first wiring prohibited area ~~as~~, when viewed in ~~said~~ the lamination direction of said multilayer substrate.

4. (Currently Amended) The high-frequency power amplifier according to claim 1, wherein one end of said first grounding conductor portion ~~is formed such that it~~ runs along a periphery of said via ~~as~~, when viewed in ~~said~~ the lamination direction of said multilayer substrate.

5. (Currently Amended) A high-frequency power amplifier comprising:

a multilayer substrate ~~formed by laminating~~ including a plurality of laminated dielectric layers;

a first wiring prohibited area ~~provided~~ located on ~~a~~ an obverse side of said multilayer substrate;

a second wiring prohibited area ~~provided~~ located on a reverse side of said multilayer substrate ~~such that~~, said second wiring prohibited area ~~is disposed at a position at which it overlaps~~ overlapping said first wiring prohibited area ~~as~~, when viewed in a lamination direction of said multilayer substrate;

a strip conductor disposed within said multilayer substrate; and

a first grounding conductor and a second grounding conductor disposed sequentially in ~~said~~ the lamination direction of said multilayer substrate and sandwiching said strip conductor~~;~~, wherein ~~a~~

length of said first wiring prohibited area in ~~said~~ the lamination direction of said multilayer substrate is equal to that of said second wiring prohibited area~~;~~, and

~~wherein~~ said first grounding conductor includes:

a first grounding conductor portion ~~provided~~ for said first wiring prohibited area; and

a second grounding conductor portion ~~provided~~ for an area on ~~said~~ the obverse side of said multilayer substrate such that ~~a position of~~ said second grounding conductor portion is positioned, in ~~said~~ the lamination direction of said multilayer

substrate ~~is~~, different from ~~that of~~ said first grounding conductor portion, ~~said~~ the area being ~~other than~~ outside said first wiring prohibited area; and

~~wherein~~ said second grounding conductor includes:

a third grounding conductor portion ~~provided~~ for said second wiring prohibited area; and

a fourth grounding conductor portion ~~provided~~ for an area on ~~said~~ the reverse side of said multilayer substrate such that ~~a position of~~ said fourth grounding conductor portion is positioned, in ~~said~~ the lamination direction of said multilayer substrate ~~is~~, different from ~~that of~~ said third grounding conductor portion, ~~said~~ the area being ~~other than~~ outside said second wiring prohibited area.